
 MATERIAL DATA FORM		Manufacturer contact Information					
		Contact Name	Compliance Coordinator				
		Tel. No.	+1 (805) 377-3648				
		E-mail address	Compliance@diodes.com				
Manufacturer's Part Number.	Total Mass of the Unit specified in (g):	Material Name	Substance Name	IMDS No.	Substance Mass (mg)	% Weight of Assembly	PPM of Total Assembly
AP5724WUG/ AP5725WUG/ AP5726WUG	0.018	Die,Analog	Doped silicon	TBD	0.6740	3.71%	37077
Customer's Partnumber.		TSOT23-6 leadframe	CDA-194	37507841	8.3002	45.66%	456601
			Die attached pad plating	37507916	0.6241	3.43%	34333
		Bonding wire	Gold	3399000	0.0845	0.47%	4651
		Molding compound	EME-G700	TBD	7.5771	41.68%	416821
		Die attach epoxy	84-1 LMISR4	TBD	0.2784	1.53%	15315
		Tin solder	Pure Tin	37508652	0.6399	3.52%	35202
					Total (mg)	18.178	

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		Manufacturer's Part Number.	Total Mass of the Unit specified in (g):	Material Name	Generic ID	Element	CAS No.	Substance Mass (mg)	% of Weight (Sub Assembly Material)	PPM of Sub Assembly Material	PPM of Total Weight	Additional Information (e.g. complete polymeric Material Trade Name or metallic Material Standard). Please declare "No FR" when the polymeric material DOES NOT contain any flame retardants.	Manufacturer Part & Version No.	Date of completion, dd/mm/yyyy	Dummy No.	Customer Project.	Diodes ECN No.	Manufacturer DUNS Number
AP5724WUG/ AP5725WUG/ AP5726WUG	0.018	Die,Analog	Doped silicon	Si	7440-21-3	0.6740	100.00%	1000000	37077									
Customer's Partnumber.		TSOT23-6 leadframe	CDA 194	Cu	7440-50-8	8.0844	97.40%	974000	444729									
				Fe	7439-89-6	0.1992	2.40%	24000	10958									
				P	7723-14-0	0.0066	0.08%	800	365									
				Zn	7440-66-6	0.0100	0.12%	1200	548									
		Bonding wire	Pure silver	Ag	7440-22-4	0.6241	100.00%	1000000	34333									
			1.0mil	Au	7440-57-5	0.0845	100.00%	1000000	4651									
		Molding compound	EME-G700	Epoxy Resin	-----	0.5683	7.50%	75000	31262									
				Phenol Resin	-----	0.3789	5.00%	50000	20841									
				Bismuth/Bismuth	-----	0.0038	0.05%	500	208									
				SiO2	60676-86-0	6.5883	86.95%	869500	362426									
				C	1333-86-4	0.0379	0.50%	5000	2084									
		Die attached epoxy	84-1 LMISR4	Ag	7440-22-4	0.2088	75.00%	750000	11486									
				epoxy resin	Trade secret	0.0557	20.00%	200000	3063									
				curing agent & hardener	Trade secret	0.0139	5.00%	50000	766									
		Tin solder	Pure Tin	Sn	7440-31-5	0.6399	100.00%	1000000	35202									
					Total (mg)	18.178												

MATERIALS DISCLOSURE DISCLAIMER	
<p>1. The materials are disclosed according to JIG-101 "Material Composition Declaration for Electronic Products"</p> <p>2. Even though all possible efforts have been made to provide you with the most accurate information, we can not guarantee its completeness and accuracy due to the fact that the data has been compiled based on information provided by our subcontractors and raw material suppliers. Complete information may not have been provided to protect their business proprietary information. Based on the above considerations, this information is provided only as estimates of the average weight of these parts and the anticipated significant toxic metals components.</p> <p>3. These estimates do not include trace levels of dopants and metal materials within the silicon devices contained inside of the finished products.</p>	
<p>This product or product family does not contain any of the following substances except CURRENTLY exempted by ELVII and RoHS and reported above:</p>	
<p>1. Antimony compounds</p> <p>2. Asbestos</p> <p>3. Azo compounds</p> <p>4. Cadmium and cadmium compounds</p> <p>5. Certain Shortchain Chlorinated Paraffins</p> <p>6. Chlorinated organic compounds</p> <p>7. Halogens</p> <p>8. Hexavalent chromium compounds</p> <p>9. Lead and lead compounds</p> <p>10. Mercury and mercury compounds</p> <p>11. Organic tin compounds</p>	<p>12. Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)</p> <p>13. Ozone Depleting Substances - Class II (HCFCs)</p> <p>14. Perfluorooctane Sulphonate (PFOS) or related compounds</p> <p>15. Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE</p> <p>16. Polychlorinated Biphenyls (PCBs)</p> <p>17. Polychlorinated Naphthalenes (>3 chlorine atoms)</p> <p>18. Radioactive Substances</p> <p>19. Tributyl Tin (TBT) and Triphenyl Tin (TPT)</p> <p>20. Tributyl Tin Oxide (TBTO)</p>
<p>This product or product family meet REACH requirements for chemicals designated by the European Chemicals Agency (ECHA) as Substances of Very High Concern (SVHC) appended below:</p>	
<p>1. Anthracene</p> <p>2. 4,4'- Diaminodiphenylmethane</p> <p>3. Dibutyl phthalate (DBP)</p> <p>4. Cyclododecane</p> <p>5. Cobalt dichloride</p> <p>6. Diarsenic pentaoxide</p> <p>7. Diarsenic trioxide</p> <p>8. Sodium dichromate, dihydrate</p>	<p>9. Bis (2-ethylhexyl)phthalate (DEHP)</p> <p>10. Hexabromocyclododecane (HBCDD)</p> <p>11. Bis(tributyltin)oxide (TBTO)</p> <p>12. Lead hydrogen arsenate</p> <p>13. Triethyl arsenate</p> <p>14. Benzyl butyl phthalate (BBP)</p> <p>15. 5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)</p> <p>16. Alkanes, C10-13, chloro (SCCPs - Short Chain Chlorinated Paraffins)</p>